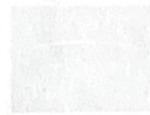


SIXTH EDITION

Solid State Electronic Devices

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This is clearly an enormous simplification compared to the more detailed problem. Obviously, the periodic crystal forces depend on the details of a specific semiconductor; therefore, the effective mass is different in different materials.

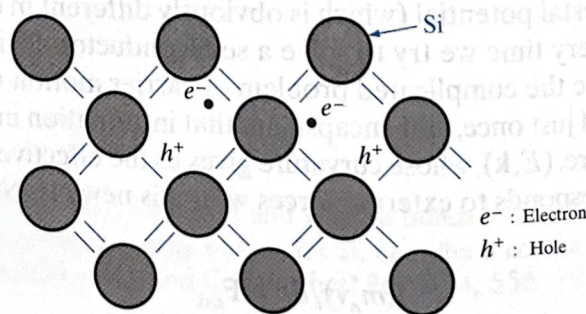
Once we determine the band curvature effective mass components from the orientation-dependent $(E, \mathbf{k})$, we have to combine them appropriately for different types of calculations. We shall see in Section 3.3.2 that when we are interested in determining the numbers of carriers in the bands, we have to use a “density-of-states” effective mass by taking the geometric mean of the band curvature effective masses, and the number of equivalent band extrema. On the other hand we will find in Section 3.4.1 that in problems involving the motion of carriers, one must take the harmonic mean of the band curvature effective masses to get the “conductivity” effective mass.

3.2.3 Intrinsic Material

A perfect semiconductor crystal with no impurities or lattice defects is called an *intrinsic* semiconductor. In such material there are no charge carriers at 0 K, since the valence band is filled with electrons and the conduction band is empty. At higher temperatures electron-hole pairs are generated as valence band electrons are excited thermally across the band gap to the conduction band. These EHPs are the only charge carriers in intrinsic material.

The generation of EHPs can be visualized in a qualitative way by considering the breaking of covalent bonds in the crystal lattice (Fig. 3-11). If one of the Si valence electrons is broken away from its position in the bonding structure such that it becomes free to move about in the lattice, a conduction electron is created and a broken bond (hole) is left behind. The energy required to break the bond is the band gap energy E_g . This model helps in visualizing the physical mechanism of EHP creation, but the energy band model is more productive for purposes of quantitative calculation. One important difficulty in the “broken bond” model is that the free electron and the hole seem deceptively localized in the lattice. Actually, the positions of the free electron and the hole are spread out over several lattice spacings and should be considered quantum mechanically by probability distributions (see Section 2.4).

Figure 3-11
Electron-hole pairs in the covalent bonding model of the Si crystal.



Since the electrons and holes are created in pairs, the conduction band electron concentration n (electrons per cm^3) is equal to the concentration of holes in the valence band p (holes per cm^3). Each of these intrinsic carrier concentrations is commonly referred to as n_i . Thus for *intrinsic material*

$$n = p = n_i \quad (3-6)$$

At a given temperature there is a certain concentration of electron-hole pairs n_i . Obviously, if a steady state carrier concentration is maintained, there must be *recombination* of EHPs at the same rate at which they are generated. Recombination occurs when an electron in the conduction band makes a transition (direct or indirect) to an empty state (hole) in the valence band, thus annihilating the pair. If we denote the generation rate of EHPs as g_i (EHP/ $\text{cm}^3\text{-s}$) and the recombination rate as r_i , equilibrium requires that

$$r_i = g_i \quad (3-7a)$$

Each of these rates is temperature dependent. For example, $g_i(T)$ increases when the temperature is raised, and a new carrier concentration n_i is established such that the higher recombination rate $r_i(T)$ just balances generation. At any temperature, we can predict that the rate of recombination of electrons and holes r_i is proportional to the equilibrium concentration of electrons n_0 and the concentration of holes p_0 :

$$r_i = \alpha_r n_0 p_0 = \alpha_r n_i^2 = g_i \quad (3-7b)$$

The factor α_r is a constant of proportionality which depends on the particular mechanism by which recombination takes place. We shall discuss the calculation of n_i as a function of temperature in Section 3.3.3; recombination processes will be discussed in Chapter 4.

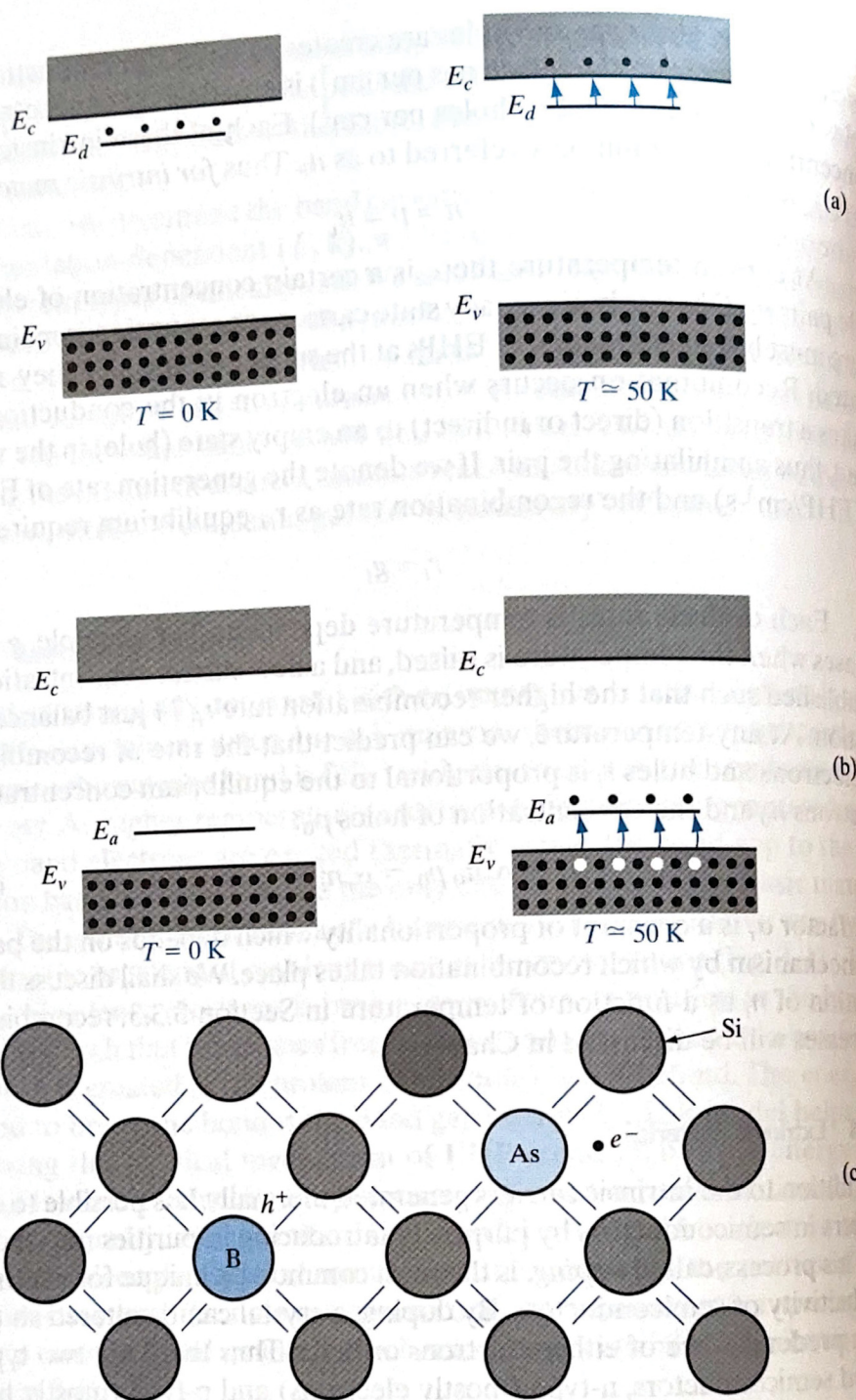
3.2.4 Extrinsic Material

In addition to the intrinsic carriers generated thermally, it is possible to create carriers in semiconductors by purposely introducing impurities into the crystal. This process, called *doping*, is the most common technique for varying the conductivity of semiconductors. By doping, a crystal can be altered so that it has a predominance of either electrons or holes. Thus there are two types of doped semiconductors, n-type (mostly electrons) and p-type (mostly holes). When a crystal is doped such that the equilibrium carrier concentrations n_0 and p_0 are different from the intrinsic carrier concentration n_i , the material is said to be *extrinsic*.

When impurities or lattice defects are introduced into an otherwise perfect crystal, additional levels are created in the energy band structure, usually within the band gap. For example, an impurity from column V of the periodic table (P, As, and Sb) introduces an energy level very near the conduction band in Ge or Si. This level is filled with electrons at 0 K, and very little thermal energy is required to excite these electrons to the conduction band (Fig. 3-12a). Thus at about 50–100 K virtually all of the electrons in the

Figure 3-12

Energy band model and chemical bond model of dopants in semiconductors: (a) donation of electrons from donor level to conduction band; (b) acceptance of valence band electrons by an acceptor level, and the resulting creation of holes; (c) donor and acceptor atoms in the covalent bonding model of a Si crystal.



impurity level are “donated” to the conduction band. Such an impurity level is called a *donor* level, and the column V impurities in Ge or Si are called donor impurities. From Fig. 3-12a we note that the material doped with donor impurities can have a considerable concentration of electrons in the conduction band, even when the temperature is too low for the intrinsic EHP concentration to be appreciable. Thus semiconductors doped with a significant number of donor atoms will have $n_0 \gg (n_i, p_0)$ at room temperature. This is n-type material.